

ALPHA[®] WSX 9200

Water Soluble - Halogen Free - High Activity - High Viscosity Flux for Semiconductor Ball-Attach

DESCRIPTION

ALPHA WSX 9200 water soluble halide free flux is engineered to be used in the attachment of lead-free or tin-lead eutectic spheres onto BGA or CSP components.

ALPHA WSX 9200 has also been designed to have excellent rolling stability on stencils for ball drop on fine pitch CSP components and wafer WLCSP applications.

It is highly compatible with Cu-OSP, electrolytic Ni-Au and ENEPIG pad finishes with best-in-class fluxing activity resulting in maximized yield.

FEATURES AND BENEFITS

- Excellent Wettability
- Halide-free Formulation
- Enhanced Cleanability
- Excellent material stability – maintains viscosity tack and viscosity over time
- Can be used in nitrogen or air environments
- Excellent print and pin-transfer stability

APPLICATION

- Pin Transfer or Ball Dip
- Screen/Stencil Print

PHYSICAL AND CHEMICAL PROPERTIES

ALPHA WSX 9200 TECHNICAL DATA		
CATEGORY	RESULTS	PROCEDURES/REMARKS
CHEMICAL PROPERTIES		
Activity Level (J-STD Classification)	ORL0	IPC J-STD-004
Halide Content	Halide free (by titration). Passes Ag Chromate Test	IPC TM-650 Test Method 2.3.35
Copper Corrosion Test (after washing)	Pass, (No evidence of Corrosion)	IPC TM-650 Test Method 2.3.32
pH (5% Solution)	5 - 7	IPC-TM-650 pH Meter
ELECTRICAL PROPERTIES		
SIR (IPC 7 days @ 85°C/85% RH)	Pass, $> 10^9$ ohms	IPC-TM-650 method 2.6.3.3 {Pass $\geq 1 \times 10^8$ ohm min}
PHYSICAL PROPERTIES		
Appearance	Brown	Visual
Tack Strength (Time-16 hrs)	> 130 gF	JIS Z 3284
Viscosity; Malcom Spiral Viscometer (@10 rpm)	600 - 1000 poise (typical)	ICPH213
Acid Number	70 - 80 (typical)	ASP-WI-QC-001FS

REFLOW

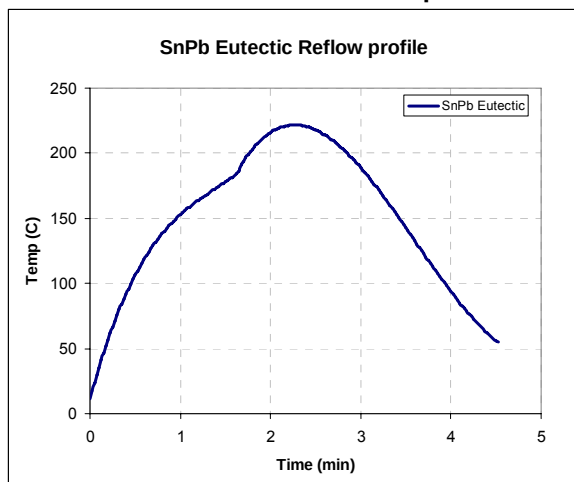
Reflow can be accomplished in an air or nitrogen controlled atmosphere, with nitrogen environments with ≤ 500 ppm oxygen levels providing improved results. The initial ramp rate should be at $0.5 - 1^\circ\text{C}$ per second to a peak temperature of $230 - 245^\circ\text{C}$ (typical lead-free alloys), or $210 - 225^\circ\text{C}$ (typical lead bearing alloys). The time over the alloy's liquidus (183°C for Sn63 or $217 - 227^\circ\text{C}$ for most SAC alloys) should be 45-90 seconds. Cooling rate should be $\geq 3^\circ\text{C}$ per second to room temperature.

REFLOW PARAMETERS (Pb free)	VALUE
Ramp rate ($^\circ\text{C}/\text{sec}$)	0.5 - 1
Typical Lead-Free Peak range ($^\circ\text{C}$)	230 -245
Time above liquidus (sec)	30 - 90
Cool down rate ($^\circ\text{C}/\text{sec}$)	> 3.0

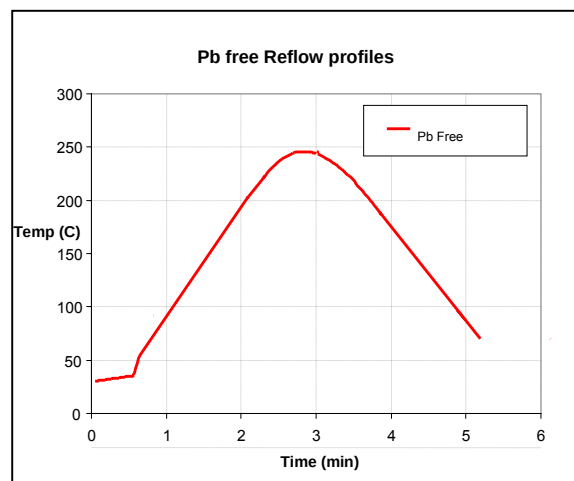
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Example reflow profiles:

SnPb Eutectic reflow profile



Pb-free Reflow Profile



RESIDUE REMOVAL

Water wash temperature 40 - 50°C without saponifier is suitable to achieve excellent results. Spray pressures of 35 to 60 psi are sufficient to remove all residues. Cleaning results using ALPHA WSX 9200 flux may exceed those achievable using traditional RMA materials.

STORAGE

This flux should be stored in sealed containers at 15°C - 25°C and should **NOT** be refrigerated. Shelf life of unopened containers is nominally 12 months. If a container has been chilled, the container should be allowed to reach room temperature before opening in order to prevent moisture condensation from ambient air onto the flux.

SAFETY

While ALPHA WSX 9200 series flux is not considered toxic, its use in typical reflow processes will generate a small amount of decomposition and reaction vapors. These vapors should be adequately exhausted from the work environment and away from personnel. Consult the Material Safety Data Sheet for additional safety information.

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